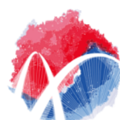

IUMRS-ICEM 2018
AUGUST 19(SUN.) - 24(FRI.), 2018 / DAEJEON, KOREA

Session Title	Microelectronics Packaging Materials and Processing II	Session Code	Th-J2
Date and Time	2018-08-23 / 13:30 - 15:30		
Place	Room J		
Session Chair	TBA		

Th-J2-1 **13:30 - 14:00**

[Invited] Various Applications of Laser based Interconnection Technology including 3D TSV Stacking Process and Flexible Modules

Kwang-Seong Choi, Leeseul Jeong, Keon-Soo Jang, Seok Hwan Moon, Hyun-Cheol Bae, and Yong-Sung Eom
ETRI, Korea

Th-J2-2 **14:00 - 14:30**

[Invited] Carbon-based Nanocomposites for Electronic Packaging Applications

Kwang-Seok Kim
KITECH, Korea

Th-J2-3 **14:30 - 14:45**

Waste Heat Recovery using Interfacial Electrical Double Layers from Oscillating Heat Pipes

Qingchen Shen, Chao Chang, Peng Tao, Ziyang Ning, Shujian Rong, Yanming Liu, Chengyi Song, Jianbo Wu, Wen Shang, and Tao Deng
Shanghai Jiao Tong Univ., China

Th-J2-4 **14:45 - 15:00**

Characterization of Cu-Inhibitor Complex Layer with AFM and Fluidics Chip System

Yeonah Jeong[1], Heon-Yul Ryu[1], Byoung-Jun Cho[1], Kwang-Min Han[1], Shohei Shima[2], Satomi Hamada[2], Hirokuni Hiyama[2], Tae-Gon Kim[3], and Jin-Goo Park[1]
[1]Hanyang Univ., Korea, [2]EBARA Corporation, Japan, [3]IMEC, Belgium